

Webinar

MSP430 to MSPM0 MCUs:
All you need to know before
you migrate

Alex Grudzinski

Product Marketing Engineering, Texas Instruments

Dennis Lehman

Applications Engineer, Texas Instruments

DeWayne Gibson

Field Applications Engineer, IAR

Agenda



- Introduction
- Welcome, history, and background
- MSPM0 vs MSP430 - overview and key differences
- Streamlining migration with IAR
- Demo: Parallel development & migration
- Q&A

MSP products

MSP MCUs

Precision analog | Ultra-low power | Easy to use

MSP430™

Up to 25MHz

16-bit

- Broad portfolio of 2000+ orderable devices optimized for ultra-low power applications
- Integrated capacitive sensing, ultrasonic sensing, sim-sam $\Sigma\Delta$ ADC's, DACs, op-amps, and LCD
- Available non-volatile FRAM memory technology with near-unlimited write endurance

1992: First MSP430 device released

MSPM0

Up to 80MHz

32-bit

- Perfect blend of cost and performance for simple 8-pin up to complex RTOS-based applications
- Pin-to-pin and software compatible across 3 performance levels and 15+ packages
- Innovation in precision analog, low energy compute, small packaging, and low cost

2023: MSPM0 MCU launch at Embedded World

MSPM0 MCUs | Scalable portfolio

Up to 125C Ta
1.62-3.6V



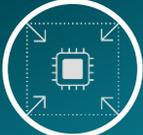
M0G
Best compute

- 80MHz CPU
- CAN-FD options
- Fast 4Msps sim-sam ADCs
- Math accelerator



M0L
Lowest power

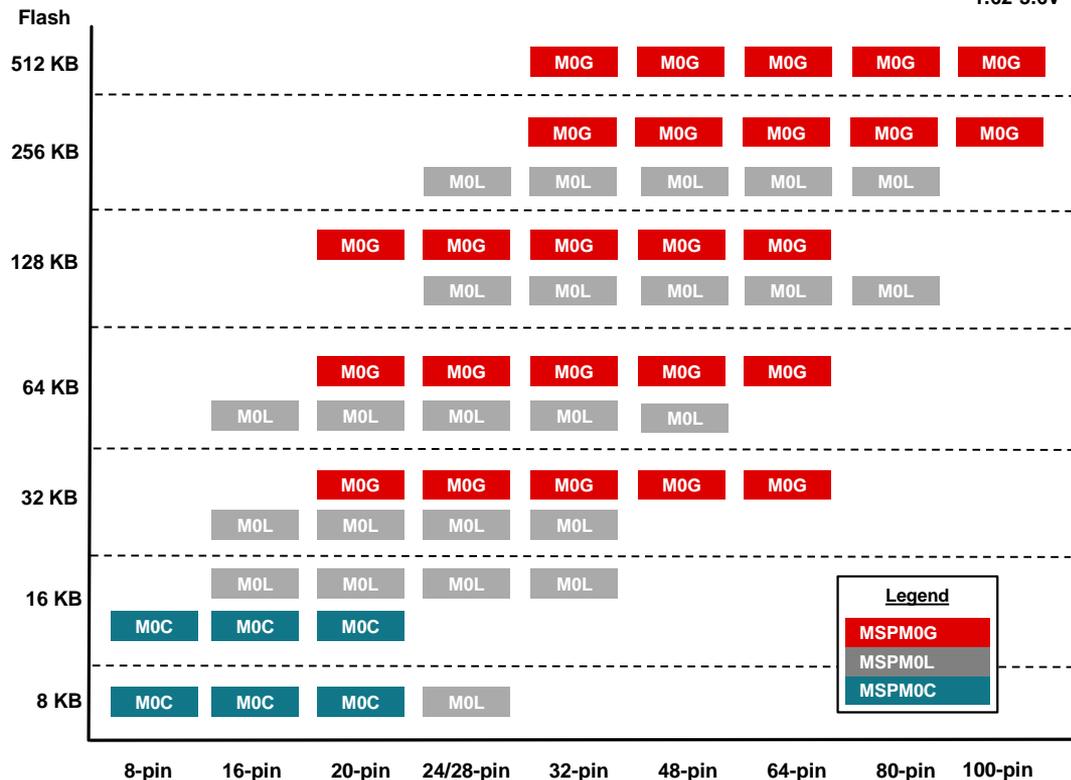
- 32MHz CPU
- 71µA/MHz (CoreMark run)
- 6µA-max standby at 85 °C
- 1µA-typ standby at 25 °C



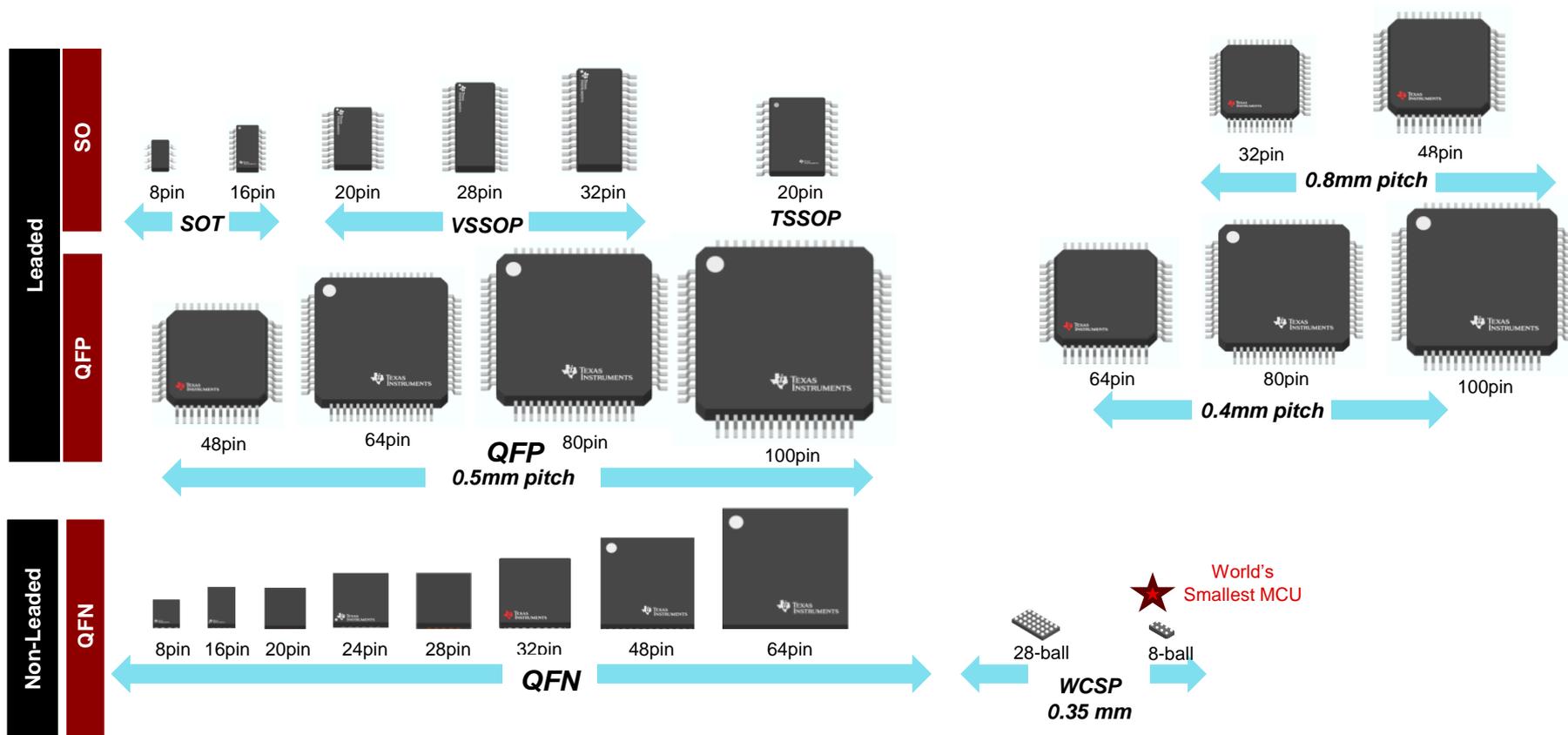
M0C
Lowest cost

- 24/32MHz CPU
- Smallest package (1.38mm²)
- 0.5/0.65mm pitch packages
- Pin-compatible with industry

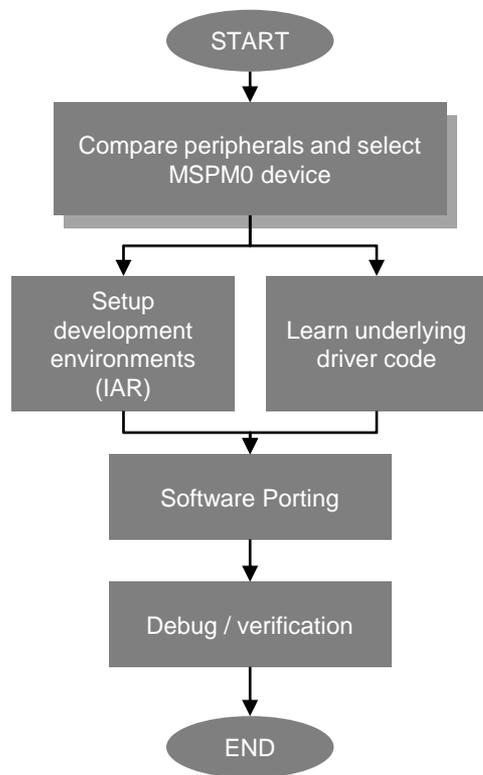
Unified software development kit & tools
Pin-to-pin compatible in 15+ packages



Ultra-small and diverse packaging portfolio

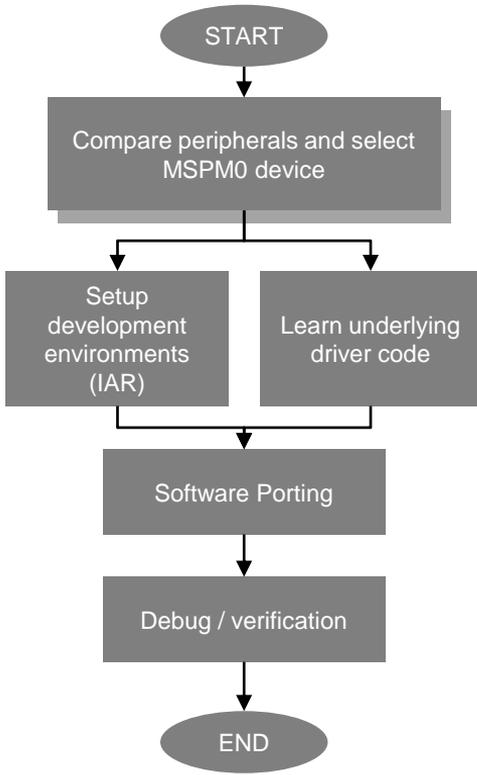


Migration considerations



	Peripheral Comparison			
	MSP430	MSPM0C	MSPM0L	MSPM0G
Core	16-bit TI proprietary	32-bit ARM M0+	32-bit ARM M0+	32-bit ARM M0+
CPU	≤ 25 MHz	24 MHz	32 MHz	80 MHz
ADC (SAR)	8,10, or 12-bit	12-bit 1.7-Msps	12-bit 1.7-Msps	12-bit 4-Msps
ADC (SD)	16 / 24-bit SD	-	-	-
COMP	Supported	-	Window compare	Window compare
DAC	8/12-bit DAC	-	8-bit DAC	12-bit DAC
UART	IrDA	LIN, IrDA, ISO7816, RS485	LIN, IrDA, ISO7816, RS485	LIN, IrDA, ISO7816, RS485
SPI	≤ 8 MHz	≤	≤ 16 MHz	≤ 32 MHz
I2C	100 kHz	Fm+ 1MHz	Fm+ 1MHz	Fm+ 1MHz
CRC	CRC16-CCITT	CRC16-CCITT	CRC16-CCITT, CRC32-ISO3309	CRC16-CCITT, CRC32-ISO3309
Timer	General, PWM, capture / compare, RTC	General, PWM, capture / compare	General, PWM, capture / compare	General, PWM, capture / compare, RTC
Special features	LCD, USS, Cap-touch, USB	-	LCD	-

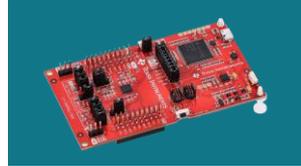
Migration considerations



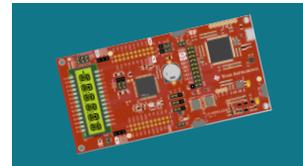
HW Evaluation Boards



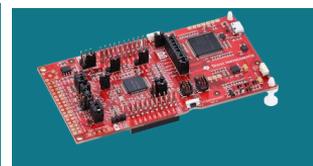
LP-MSPM0C1104



LP-MSPM0L1306



LP-MSPM0L2228



LP-MSPM0G3507

Development Environment



TI Code Composer Studio
Build, debug, analyze, and optimize



IAR Embedded Workbench
Development toolchain
Compiler, debugger, & analysis tools

Programming & Debugging



TI XDS110
Debugger



Elprotronic C-Gang
Programmer



Segger J-LINK
Debugger / tracer

Streamlining migration with IAR

What embedded teams need for migration

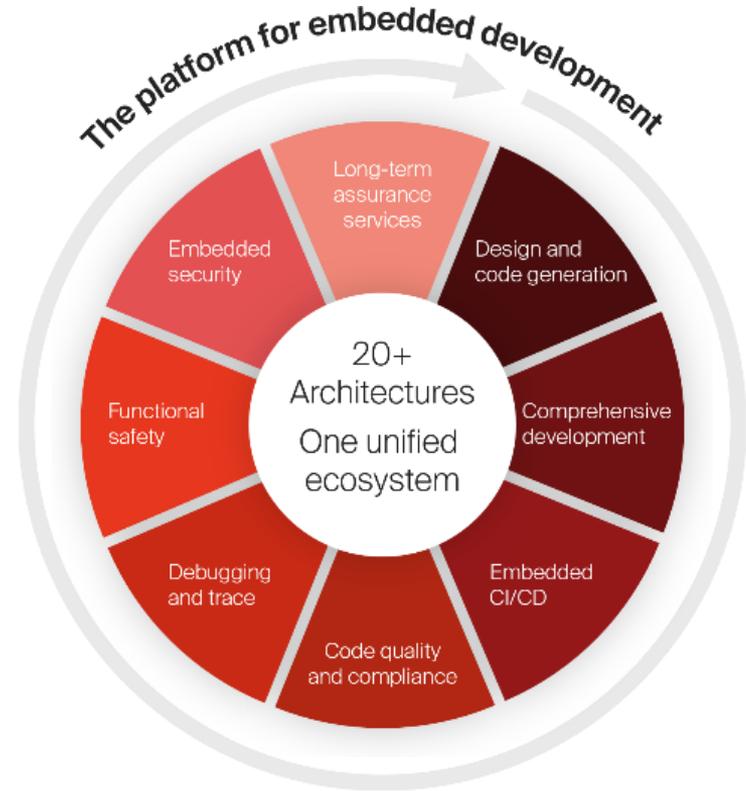


- A unified, architecture-agnostic development environment
- One toolchain to work across MSP430 and MSPM0
- Pre-certified tools ready for cloud-based builds and CI/CD
- Flexibility to migrate at their own pace, without halting progress

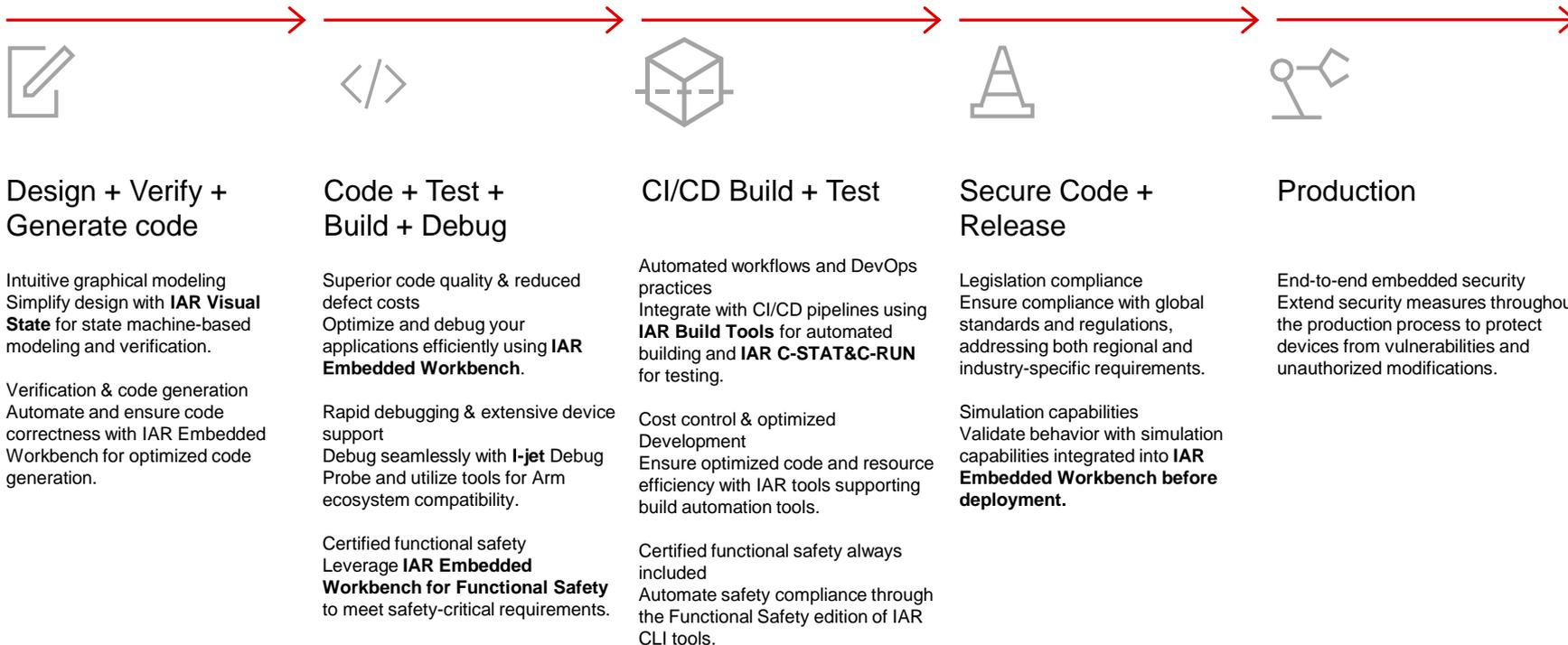
The platform for embedded development from IAR



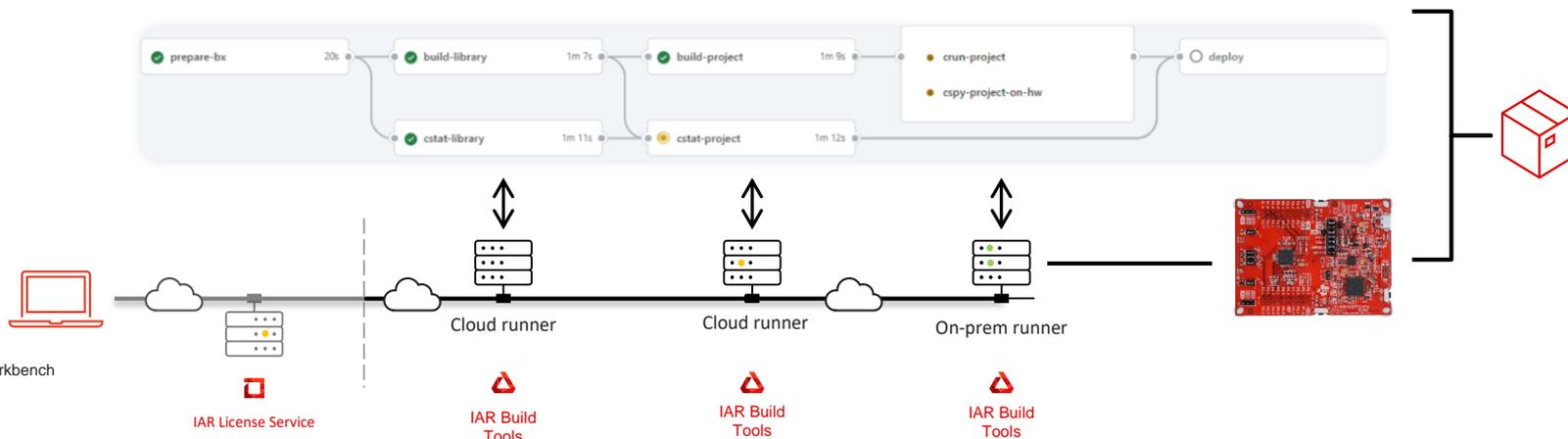
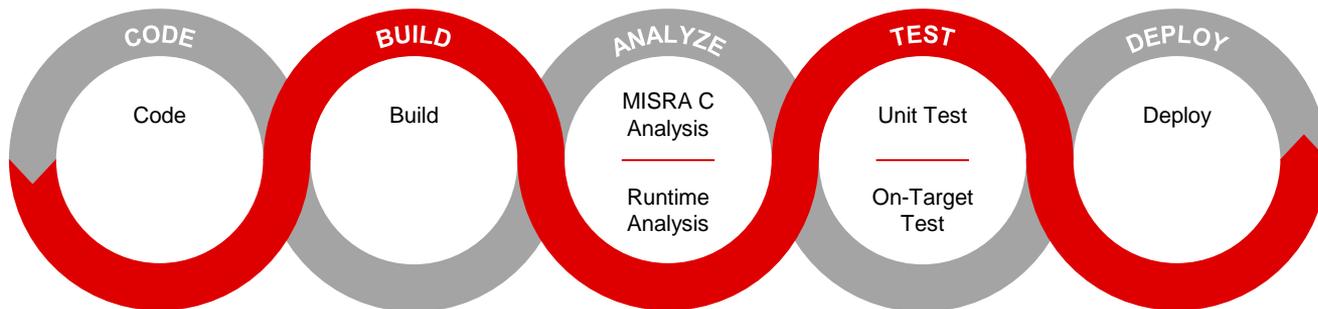
- IAR's platform is built on a transformative palette of solutions, enabling:
 - End-to-end development: From design and code generation to debugging, trace, and compliance.
 - Built-in safety & security: For mission-critical applications.
 - Scalable automation: CI/CD workflows and code quality tools.
 - Optimized embedded products: Ensuring high quality and reliability.
 - One SaaS subscription gives you full access to all IAR solutions (MSPM0(Arm), MSP430,...).



Workflow: From code-creation to the assembly line



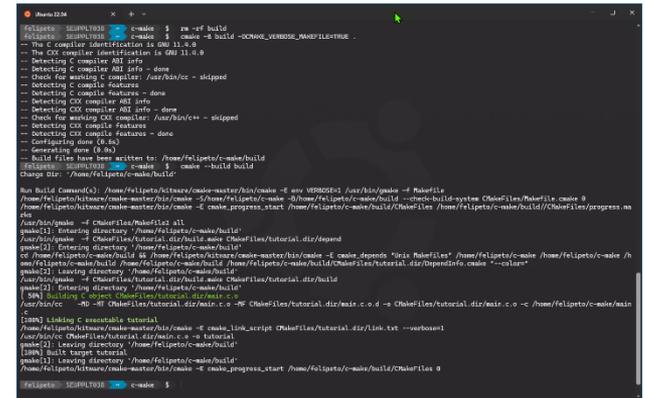
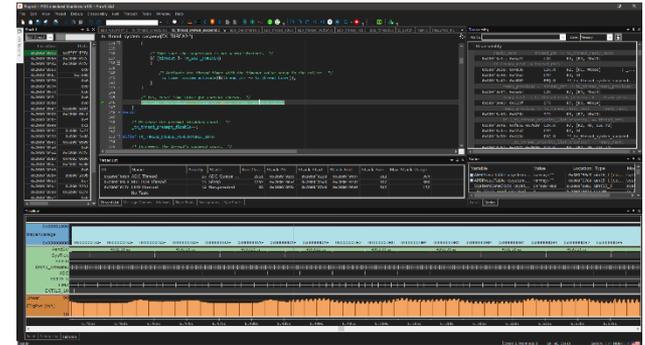
Agile embedded CI/CD workflows for MSPM0



Simplifying debugging with IAR tools



- Use IAR's C-SPY debugger to pinpoint issues faster.
- Get real-time visibility into embedded systems.
- Capture and analyze data from multiple sources.
- Reduce manual test/debug loops and speed up iterations.



Relevant functional safety standards



- Support for ISO 26262, IEC 61508, IEC 62304 and more for MSPM0 (Arm)
- This alignment will support:
 - Reproducible, auditable builds integrated directly into CI/CD pipelines.
 - Faster validation cycles and reduced risk of human error in safety-critical deployments.

								
Arm								

Parallel development strategies and project migration checklist

Parallel development & gradual migration



- Maintain MSP430 & MSPM0 projects side-by-side
- Use HAL & BSP for module isolation
- SysConfig-generated configs integrate into IAR
- Gradual migration: port drivers, test, expand
- Supported debug probes:
 - MSP430: MSP-FET (JTAG or Spy-Bi-Wire).
 - MSPM0: IAR I-jet, XDS110 or SEGGER J-Link (SWD).
 - Update connections: MSP430 uses 14-pin; MSPM0 uses 10-pin JTAG or 20-pin TI.
 - Use EnergyTrace (MSPM0) for power profiling if needed.

Recommended checklist for migration



- ✓ Set up IAR Embedded Workbench/IAR Build Tools with MSP430 and MSPM0 support.
- ✓ Use MSPM0 SDK + SysConfig for project setup.
- ✓ Map MSP430 peripherals to MSPM0 equivalents.
- ✓ Validate memory access, apply wait states if needed.
- ✓ Update interrupt/event handling for event manager.
- ✓ Switch debugger to I-jet/XDS110/J-Link, verify connections.
- ✓ Run full debug and validation cycles, including analog interfaces (ADC, COMP, OPA).

Demo migrating MSP430 projects to MSPM0

Summary

The IAR Platform is your migration accelerator



- Integrated code quality, security, and safety standards
- CI/CD-ready build environment with automation support
- Advanced debugging, profiling, and power analysis
- Flexible strategies for gradual, parallel migration
- Full support for MSP430 and MSPM0 projects side by side

Be the best and build what's next



- Learn how the IAR platform accelerates your migration journey and CI/CD transformation.
- Experience the full IAR ecosystem, from MSP430 to MSPM0, with integrated tools for quality, safety, and automation.
- Experience the full platform. Contact us and request your trial now.

Q&A

With TI and IAR experts



© Copyright 2025 Texas Instruments Incorporated. All rights reserved.

This material is provided strictly “as-is,” for informational purposes only, and without any warranty.
Use of this material is subject to TI’s **Terms of Use**, viewable at [TI.com](https://www.ti.com)

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2025, Texas Instruments Incorporated